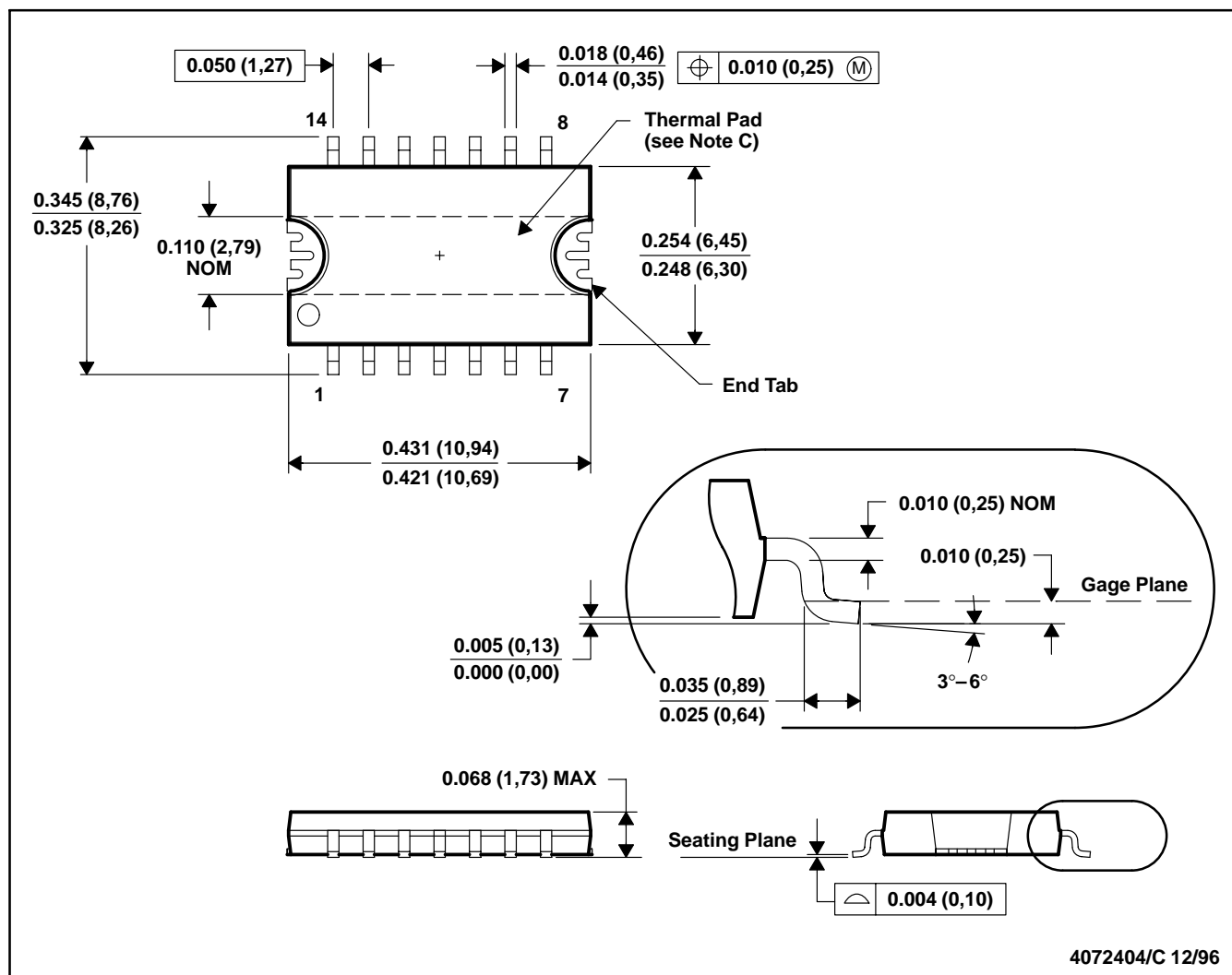


DBX (R-PDSO-G14)

PowerFLEX™ PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. The solderable pad is electrically and thermally connected to the backside of the die.

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